



Semiconductor Device Type: B3X-DFN-8-2x3x0.9mm-MatteTin

Material	Substance	CAS Number	Mass of Substance in Material (mg)	Mass of Material (mg)	Percentage of Substance in Material	Percentage of Material in Product	Percentage of Substance in Product	Amount of Substance in Product (ppm)
Die				0.51	100.00%	3.26%		
	Silicon	7440-21-3	0.51		100.00%		3.26%	32588
Plating and Anode Ball				0.41	100.00%	2.62%		
	Lead	7439-92-1	0.00		0.05%		0.00%	13
	Tin	7440-31-5	0.41		99.95%		2.62%	26185
Bond Wire				0.11	100.00%	0.70%		
	Gold	7440-57-5	0.11		100.00%		0.70%	7028
Mold Compound				7.68	100.00%	49.07%		
	Epoxy Resin	Trade Secret	0.54		7.00%		3.44%	34351
	Phenolic Resins	Trade Secret	0.38		5.00%		2.45%	24537
	Silica (Fused)	60676-86-0	5.76		75.00%		36.81%	368051
	Silicon Dioxide	7631-86-9	0.54		7.00%		3.44%	34351
	Metal Hydroxide	Trade Secret	0.38		5.00%		2.45%	24537
	Carbon Black	1333-86-4	0.08		1.00%		0.49%	4907
Die Attach				0.14	100.00%	0.89%		
	Silver	7440-22-4	0.10		67.90%		0.61%	6074
	Carbocyclic Acrylate	Trade Secret	0.03		20.00%		0.18%	1789
	Bismaleimide Resin	Trade Secret	0.01		5.50%		0.05%	492
	Acrylate or Acrylic	Trade Secret	0.01		5.50%		0.05%	492
	Epoxy cyclohexylethyltrimethoxysilane	3388-04-3	0.00		0.55%		0.00%	49
	Palladium Compound	Trade Secret	0.00		0.55%		0.00%	49
Lead Frame Plating				0.34	100.00%	2.17%		
	Silver	7440-22-4	0.34		100.00%		2.17%	21725
Lead Frame				6.46	100.00%	41.28%		
	Copper	7440-50-8	6.29		97.36%		40.19%	401874
	Iron	7439-89-6	0.16		2.42%		1.00%	9994
	Lead	7439-92-1	0.00		0.01%		0.00%	43
	Phosphorus	7723-14-0	0.01		0.11%		0.04%	435
	Zinc	7440-66-6	0.01		0.11%		0.04%	435
Totals			15.65	15.65		100.00%	100.00%	1000000

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